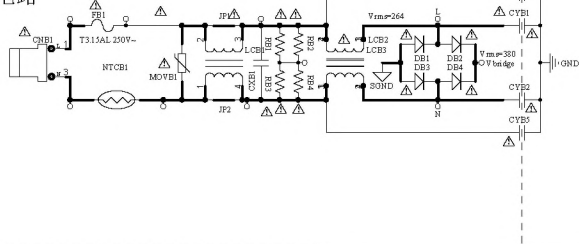
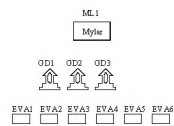


EMI电路



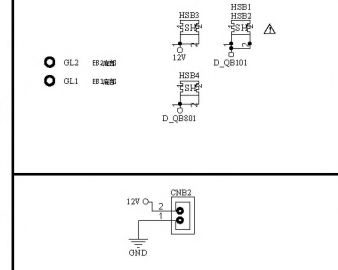
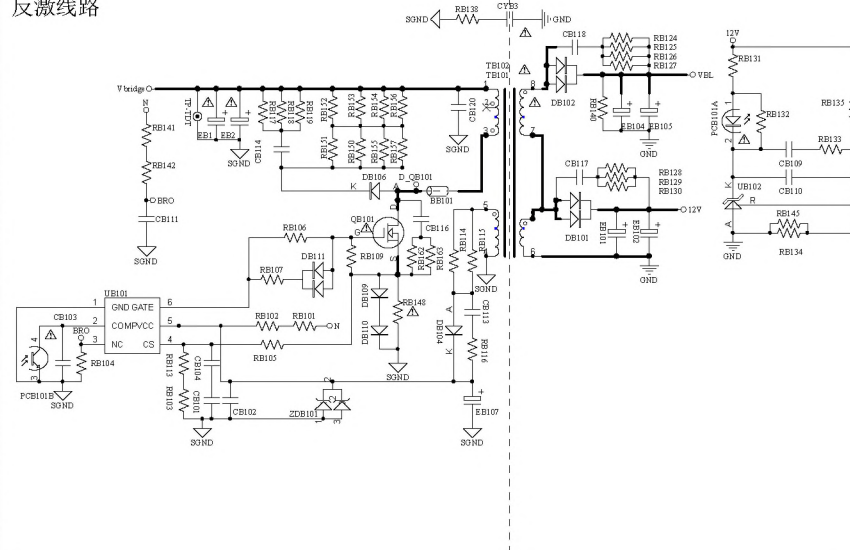
辅料及结构件等



原理图中未体现的辅料及特殊生产工艺

工艺	位号

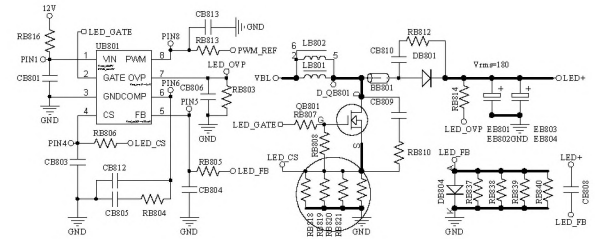
反激线路



Design Note:

Layout Note:

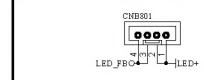
恒流线路



与TV端连接网络



辅料及结构件等



选择背光LED时请确认LED无缺陷并附
背光LED的规格书并和供应商沟通封装，做8.0M时可直接更改参数，不可动封装

Layout Note:

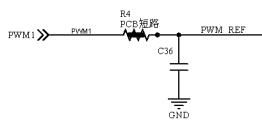
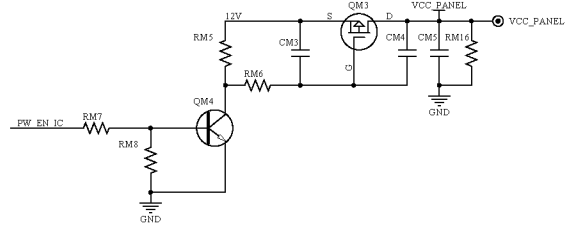
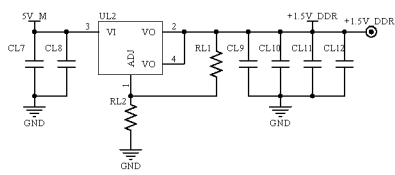
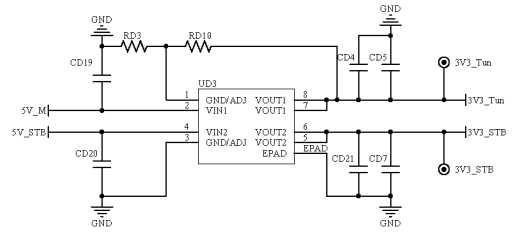
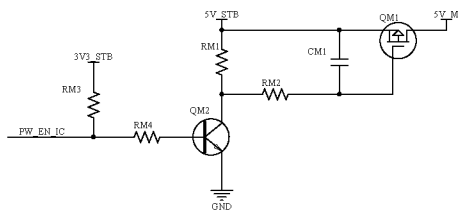
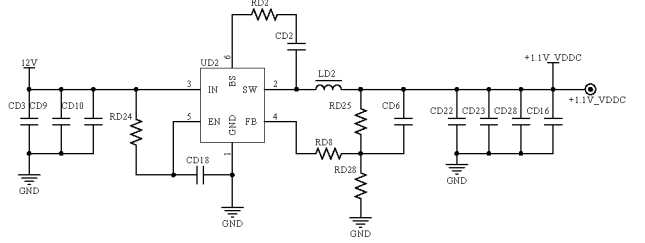
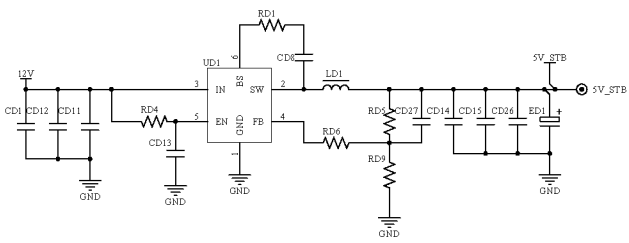
1. 解的驱动电阻电路的封装要短而C的短；
2. I2C的接收先选择单点接到恒流电阻的焊盘；
3. Mo的给源引脚与恒流电阻引脚尽量靠近，且Mo的给源引脚尽量短；
4. I2C的4、5、6、7脚跨接要远离动态区域，如Mo的D极，驱动器件等；

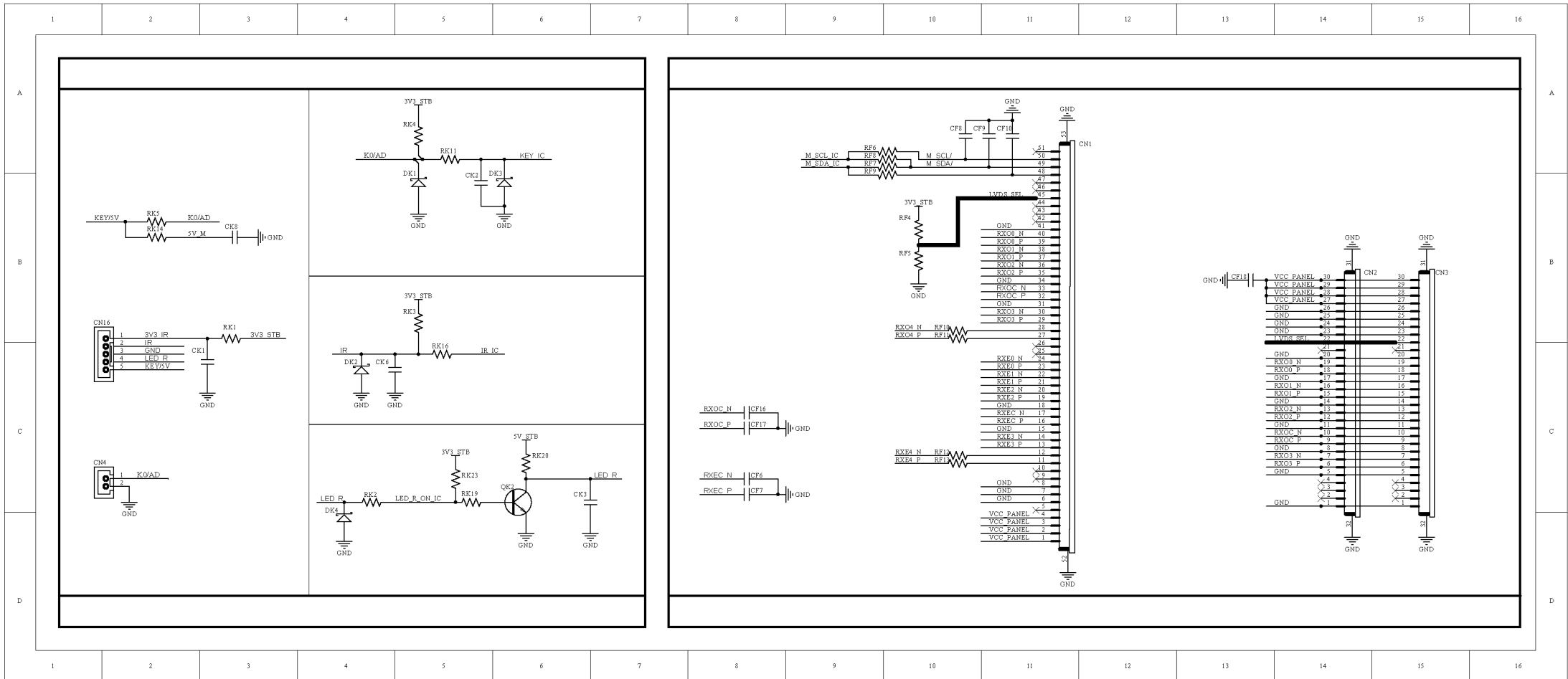
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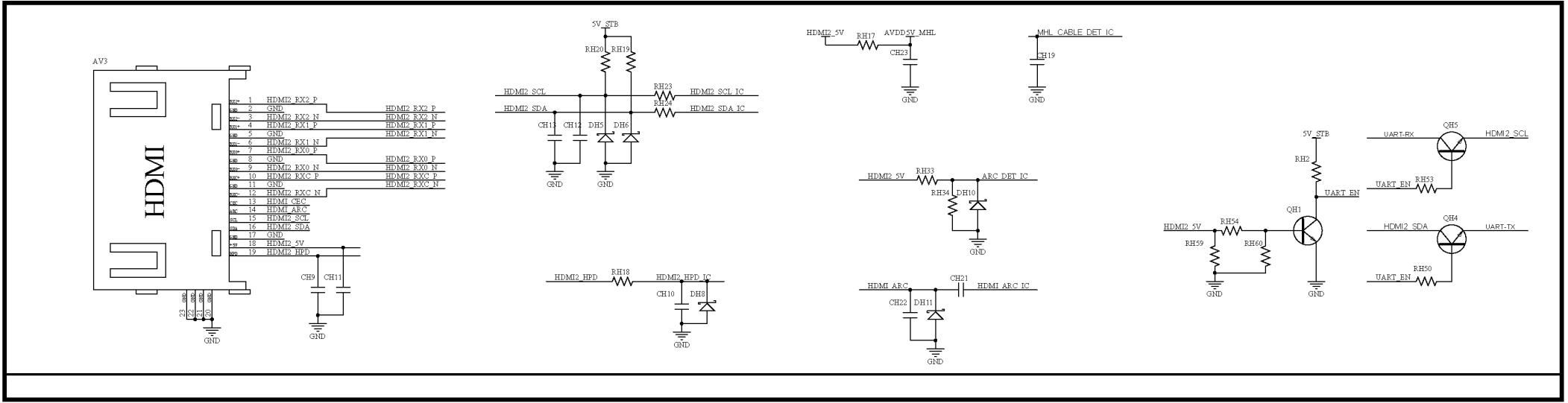
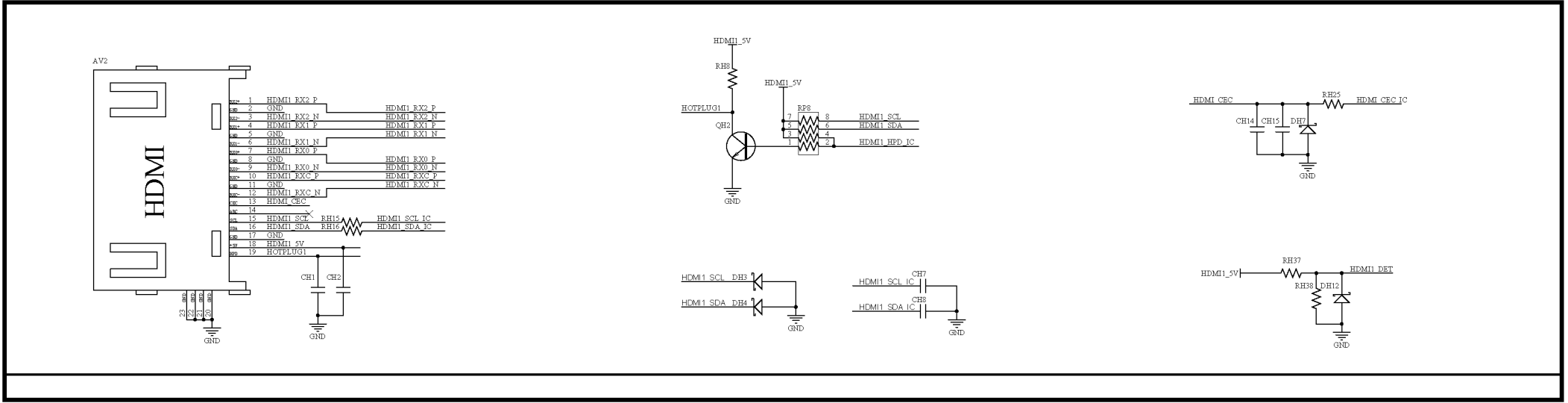
1. 88801封装使用3mm；

Model Name:	TP300X20X-A00X	VERSION:	v1.0
DRAWN:	XXX	DATE:	2015-0X-XX
CHKD:	XXX	DATE:	2015-0X-XX



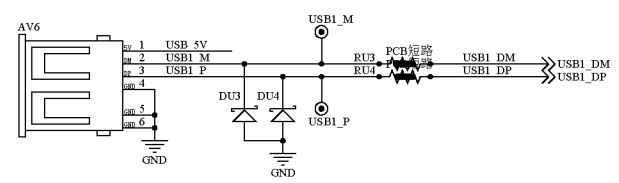
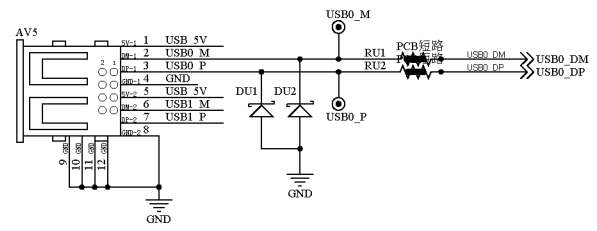
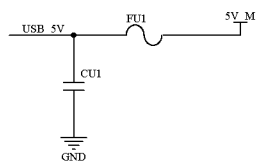






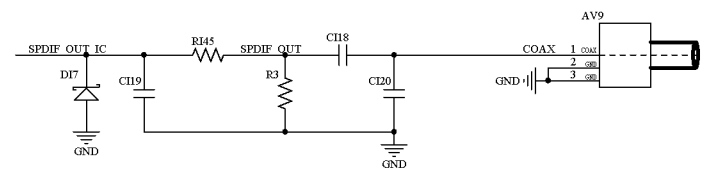
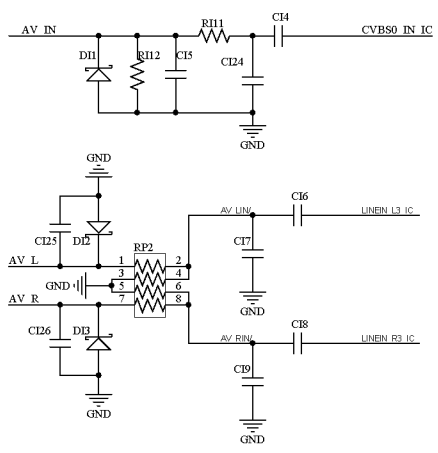
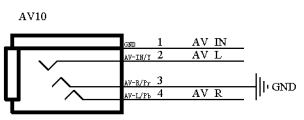
A

A



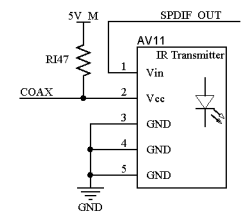
B

B



C

C

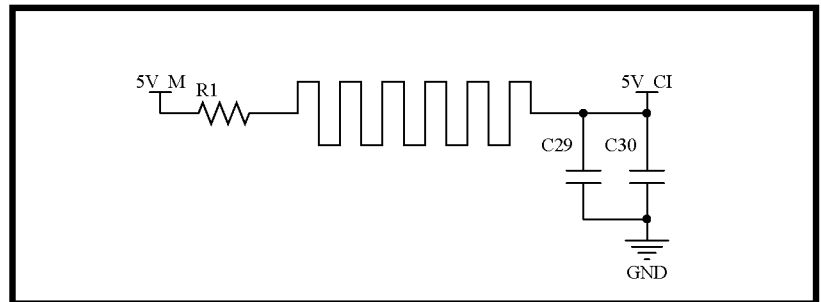
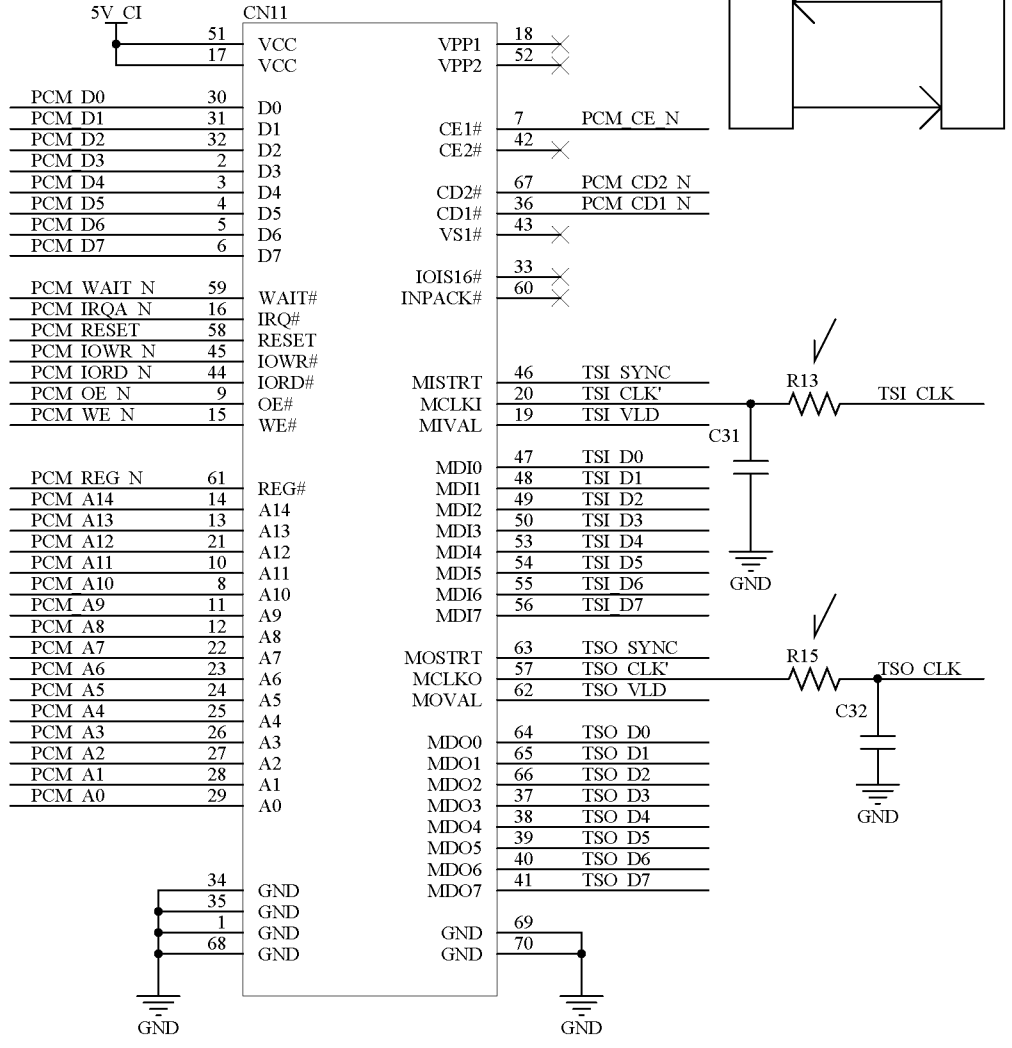


D

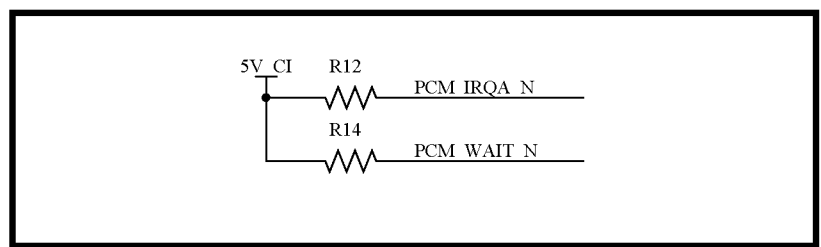
D

A

A



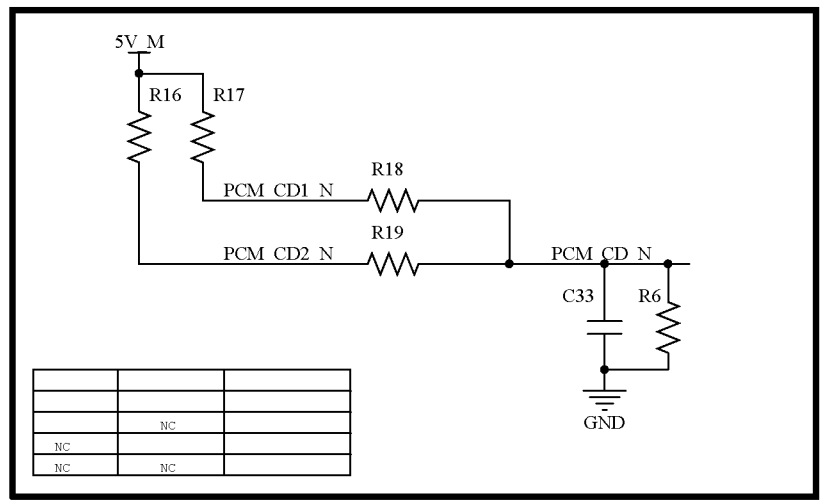
B



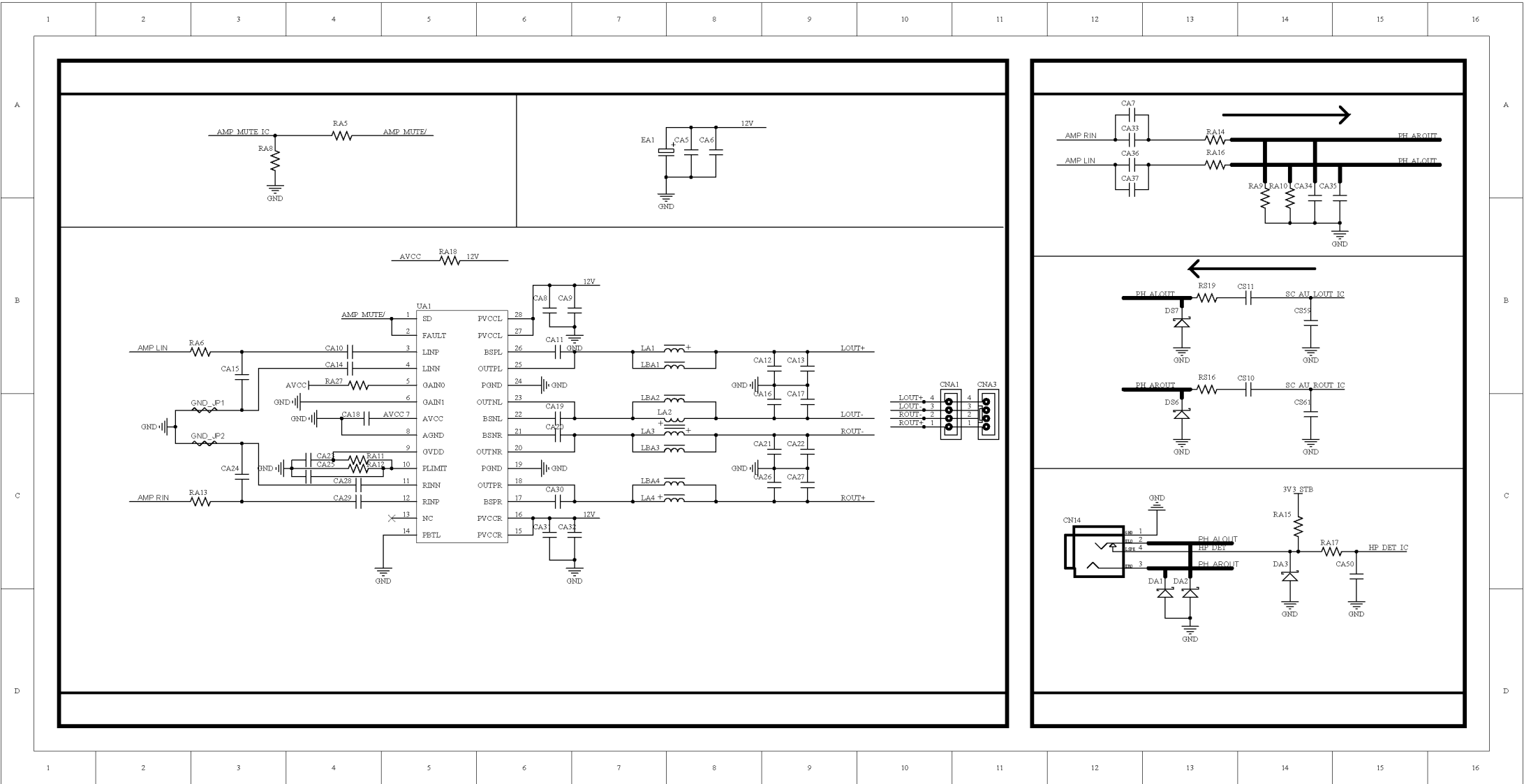
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C

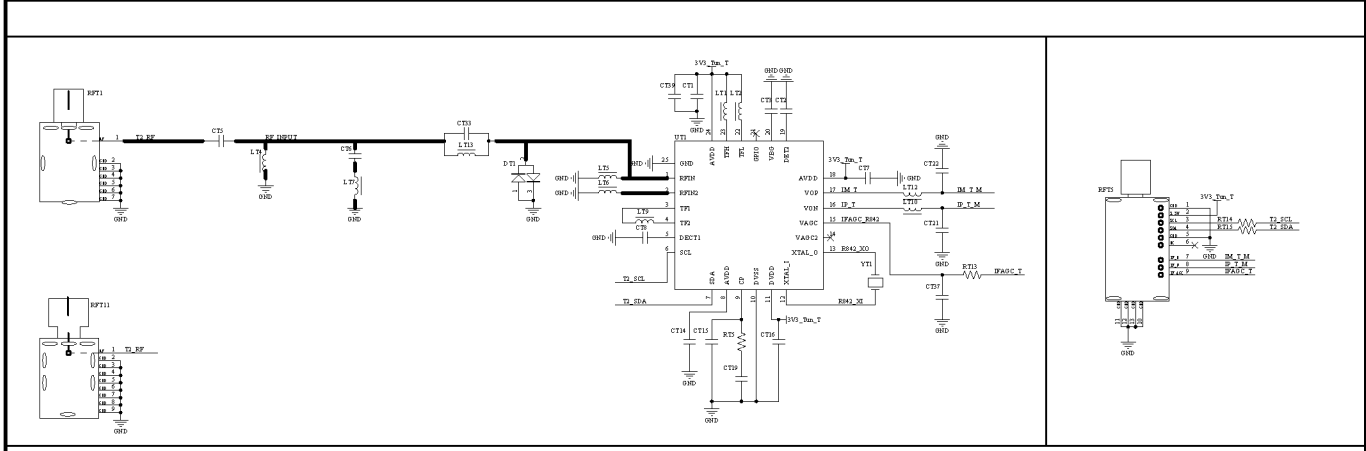
C



D

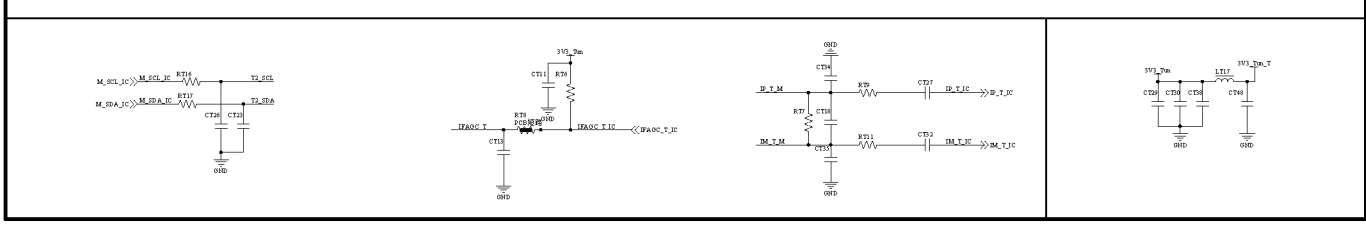


A



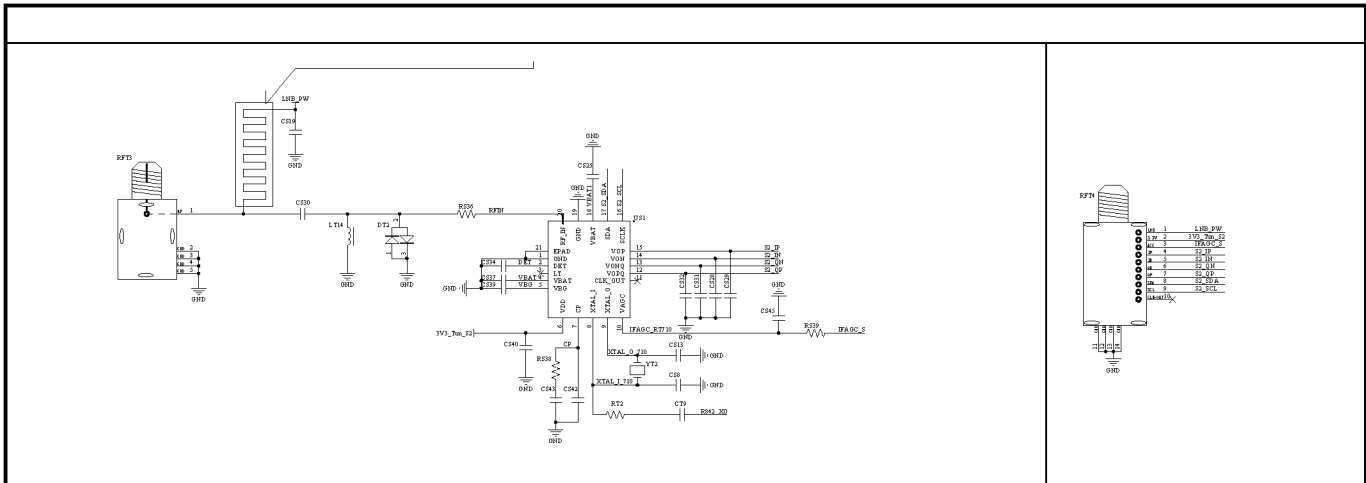
A

B



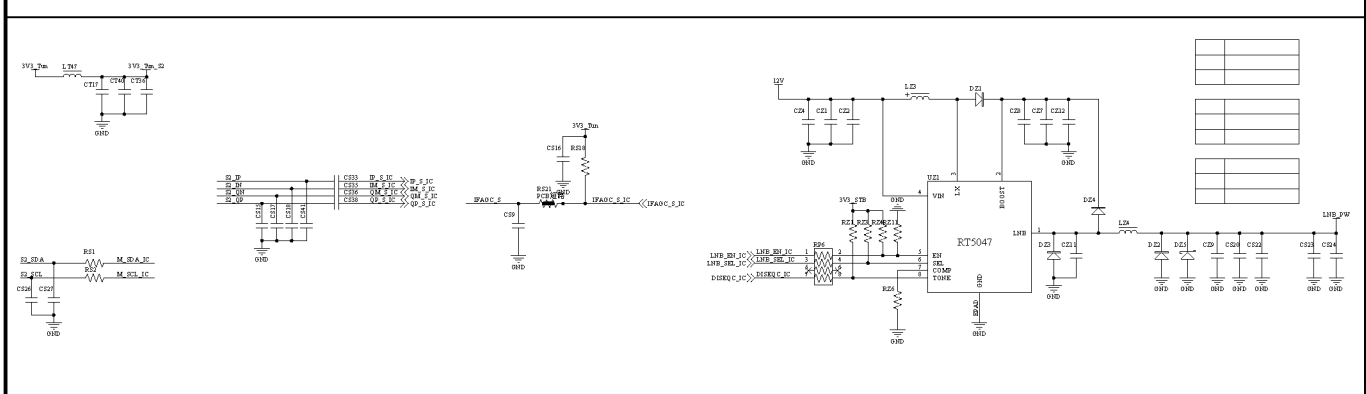
B

C



C

D



D